1SMF5920B

2.5 Watt Zener Diode in Flat Lead Package

This complete new line of 2.5 Watt Zener Diodes are offered in highly efficient micro miniature and space saving surface mount design. Because of its small size, it is ideal for use in cellular phones, portable devices, business machines and many other industrial/consumer applications.

Features

- Zener Breakdown Voltage: 6.2 V
- Low Leakage < 5 μA
- ESD Rating of Class 3 (> 16 kV) per Human Body Model
- Small Footprint Footprint Area of 8.45 mm²
- Low Profile Maximum Height of 1.0 mm
- Supplied in 8 mm Tape and Reel 3,000 Units per Reel
- Cathode Indicated by Polarity Band
- Lead Orientation in Tape: Cathode Lead to Sprocket Holes
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Mechanical Characteristics:

CASE: Void-free, transfer-molded, thermosetting plastic

Epoxy Meets UL 94 V-0

LEAD FINISH: 100% Matte Sn (Tin)

MOUNTING POSITION: Any

QUALIFIED MAX REFLOW TEMPERATURE: $260^{\circ}\mathrm{C}$

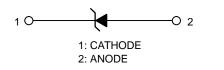
Device Meets MSL 1 Requirements



ON Semiconductor®

http://onsemi.com

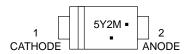
PLASTIC SURFACE MOUNT 2.5 WATT ZENER DIODE 6.2 VOLTS





SOD-123FL CASE 498

MARKING DIAGRAM



5Y2 = Device Code M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
1SMF5920BT1G	SOD-123FL (Pb-Free)	3000/Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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MAXIMUM RATINGS

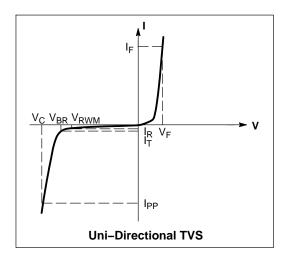
Rating	Symbol	Value	Unit
DC Power Dissipation @ T _A = 25°C (Note 1) Derate above 25°C Thermal Resistance, Junction–to–Ambient	P_{D} $R_{ heta JA}$	350 2.9 350	mW mW/°C °C/W
Thermal Resistance, Junction-to-Lead	$R_{ hetaJL}$	30	°C/W
Maximum DC Power Dissipation (Notes 1 and 2)	P_{D}	2.5	W
Operating and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Mounted with recommended minimum pad size, PC board FR-4.
- 2. At lead temperature 75°C

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted, $V_F = 1.5$ V Max. @ $I_F = 200$ mA for all

Symbol	nbol Parameter			
I _{PP}	Maximum Reverse Peak Pulse Current			
V _C Clamping Voltage @ I _{PP}				
V _{RWM} Working Peak Reverse Voltage				
I _R	Maximum Reverse Leakage Current @ V _{RWM}			
V _{BR}	Breakdown Voltage @ I _T			
Ι _Τ	Test Current			
I _F	Forward Current			
V _F	Forward Voltage @ I _F			



ELECTRICAL CHARACTERISTICS (T_L = 30°C unless otherwise noted, V_F = 1.25 Volts @ 200 mA)

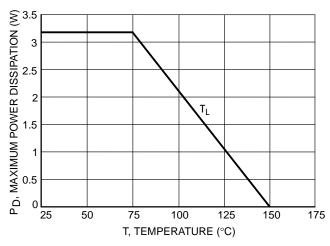
		Zener Voltage (Note 3)					Z _{ZT} @ I _{ZT}	Z _{ZK} @ I _{ZK}		
	Device	V _Z @ I _{ZT} (Volts)		I _{ZT}	I _R @ V _R	V_R	(Note 4)	(Note 4)	I _{ZK}	
Device	Marking	Min	Nom	Max	(mA)	(μΑ)	(V)	(Ω)	(Ω)	(mA)
1SMF5920BT1G	5Y2	5.89	6.2	6.51	60.5	5.0	4.0	2.0	200	1.0

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- Zener voltage is measured with the device junction in thermal equilibrium with an ambient temperature of 25°C.
 Zener Impedance Derivation Z_{ZT} and Z_{ZK} are measured by dividing the AC voltage drop across the device by the AC current applied. The specified limits are for I_Z(ac) = 0.1 I_Z(dc) with the ac frequency = 60 Hz.

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TYPICAL CHARACTERISTICS



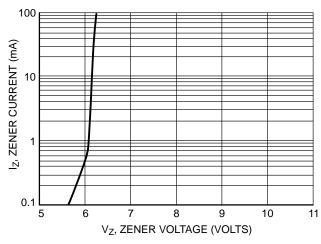
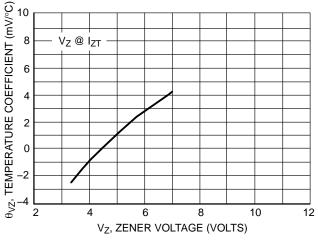


Figure 1. Steady State Power Derating

Figure 2. V_Z



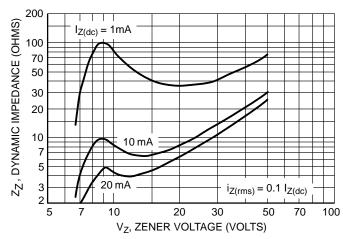
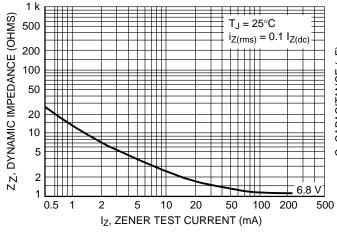


Figure 3. Zener Voltage

Figure 4. Effect of Zener Voltage



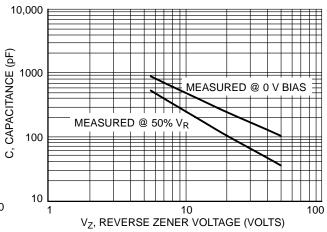


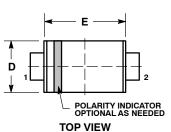
Figure 5. Effect of Zener Current

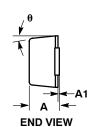
Figure 6. Capacitance versus Reverse Zener Voltage

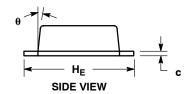


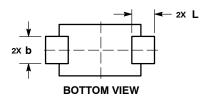
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DATE 10 MAY 2013

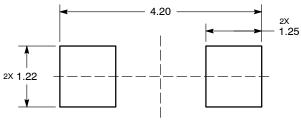








RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

NOTES:

- ES:
 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH.
 DIMENSIONS D AND J ARE TO BE MEASURED ON FLAT SECTION
 OF THE LEAD: BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.

	М	ILLIMETE	RS	INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.90	0.95	0.98	0.035	0.037	0.039	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
b	0.70	0.90	1.10	0.028	0.035	0.043	
С	0.10	0.15	0.20	0.004	0.006	0.008	
D	1.50	1.65	1.80	0.059	0.065	0.071	
E	2.50	2.70	2.90	0.098	0.106	0.114	
L	0.55	0.75	0.95	0.022	0.030	0.037	
HE	3.40	3.60	3.80	0.134	0.142	0.150	
θ	0°	-	8°	0°	-	8°	

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

= Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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DESCRIPTION:	SOD-123FL		PAGE 1 OF 1		

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^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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